

6~8wafers Fully automatic de-edge cleaning machine

Model: SA-DECM-48LS

SA-DECM-48LS adopts vacuum handling structure for stable wafer conveying and precise edge trimming. It features fully automated loading and unloading and water recycling design for energy conservation. Key electrical parts are treated with anti-corrosion measures and gas protection. With reliable control system and perfect leakproof design, it operates safely and conforms to semiconductor industrial standards.



Feature

- Automatic Loading and Unloading
- Vacuum Suction Cup
- Pure Water Reuse
- FPA Anti-corrosion Isolation
- ISO9001 Quality Assurance

Application

- Wafer Front-End Cleaning
- Photolithography Cleaning
- Etch Post-Cleaning
- Thin Film Cleaning
- Back-End Packaging

Specifications:

Parameter	Descriptions
Wafer Size	6"~8"
Edge Trimming Accuracy	±0.1mm
Control Part	PLC and HMI
Gas Projection	CDA/N ₂